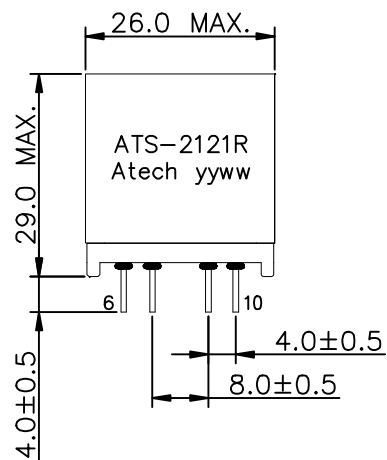
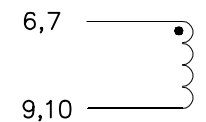


PIN 1,2,3,4,8 CUT OFF



ELECTRICAL CHARACTERISTICS:

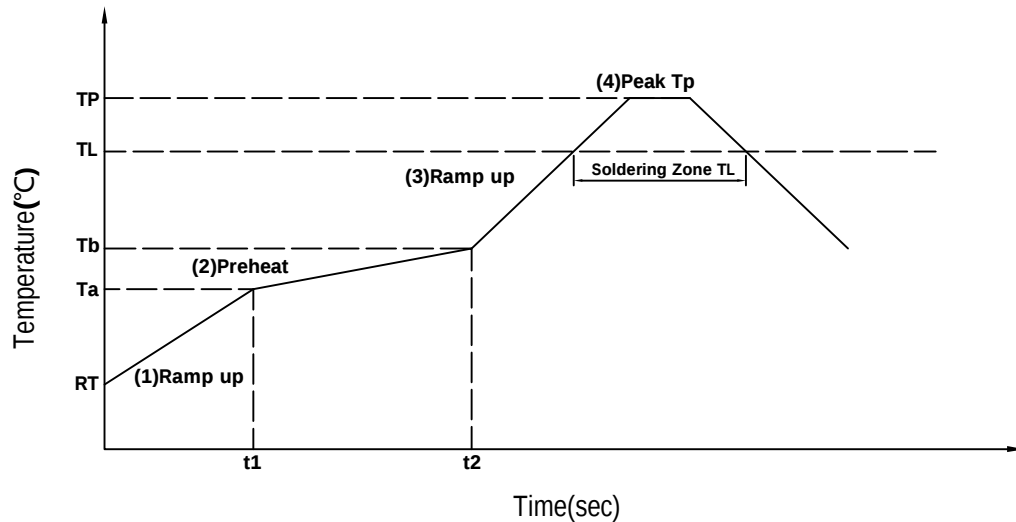
1. DCR : PIN 6,7 - 9,10 = 16mΩ MAX.
2. INDUCTANCE (@100kHz, 1Vrms) : PIN 6,7 - 9,10 = 22uH ±10%
- 3.DC BIAS (@100kHz, 1Vrms) : L(14A) = L(6,7 - 9,10) * 80% MIN.
4. Q (@100kHz, 1Vrms) : PIN 6,7 - 9,10 = 60 MIN.
5. Hi-POT (@600Vac, 1mA, 3SEC) : PIN 6,7 - CORE
6. RoHS COMPLIANT

UNIT : mm

								TITLE TRANSFORMER	
								DWG. NO. ATS-2121R	
	RELEASE	12/28/2020	SHIRLEY	EVAN	EVAN	UNITS: M/M	SAFETY	SHEET 1 OF 1	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 12/28/20		P/N:	DRAW Shirley
REVISIONS									



Pb-free Soldering IR Reflow(SMD)

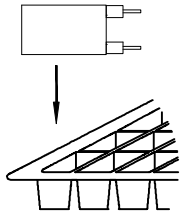


- 1,MSL Grade: 1 Level 2,Floor life: 2years 3,Condition:≤30°C RH 85%
2,Form-1(Reference JEDEC J-STD-020D Table 5-2)

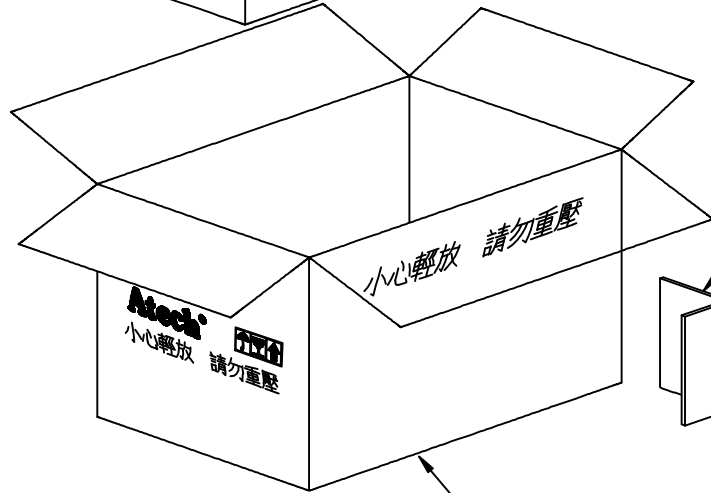
IR reflow profile		Pb-free
step#	Profile Feature	Condition/Duration
step1	Ramp-up rate	3°C/second max
step2	Preheat:150°C-200°C(Ta-Tb)	t1-t2:60-120seconds
step3	Ramp-up rate(TL to Tp)	3°C/second max
	Temperature maintained above 217°C	60-150seconds
step4	Peak temperature(Tp)	260+0/-5°C
	Time within 5°C of actual peak temperature	30seconds max
Ramp-down rate(Tp to TL)		6°C/second max

- 3,Form-2(Reference JEDEC J-STD-020D Table 4-2)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6mm	260+0/-5°C	260+0/-5°C	260+0/-5°C
1.6mm-2.5mm	260+0/-5°C	250+0/-5°C	245+0/-5°C
>2.5mm	250+0/-5°C	245+0/-5°C	245+0/-5°C



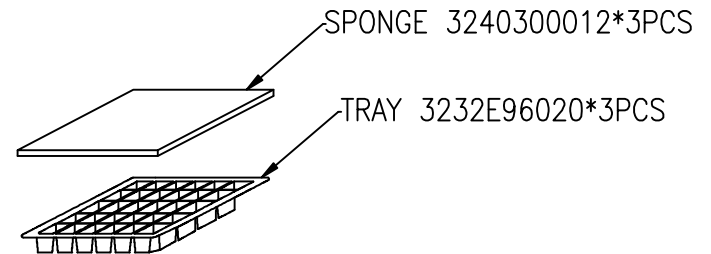
(3212718000 Box)*6PCS



外箱四棱角處加護角
32B0402700*4PCS

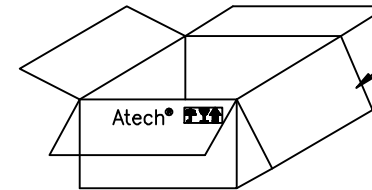
(3214029000 CARTON) *1PCS

ONE TRAY : 30 PCS
INNER BOX : 3 TRAY
ONE CARTON : 6 BOXES(540PCS)



SPONGE 3240300012*3PCS

TRAY 3232E96020*3PCS

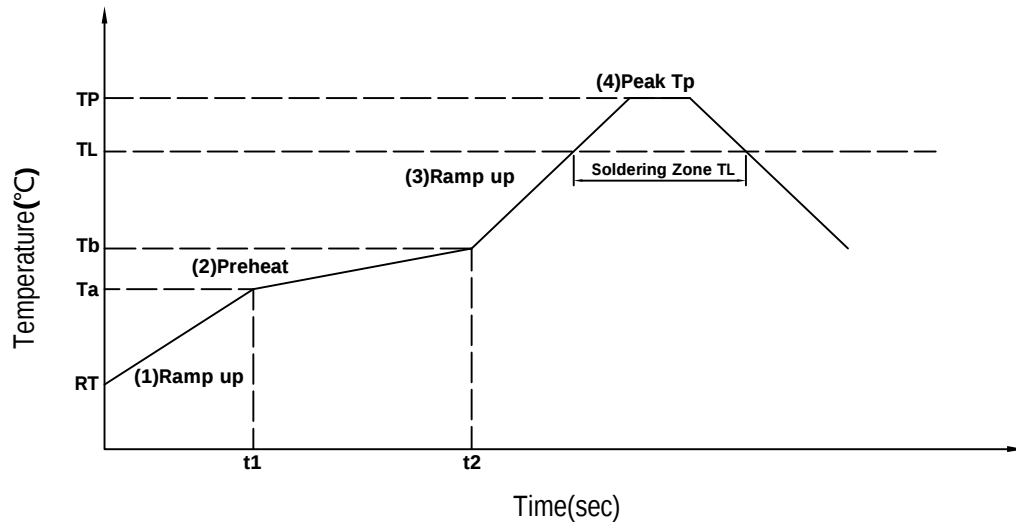


(3212718000 box)*1PCS

								TITLE		PCAKING	
								DWG. NO.		968S212100	
	RELEASE	04/19/2021	SHIRLEY	TINA	TINA	UNITS: M/M		SAFETY		SHEET 1 of 1	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE		P/N:		DRAW	
REVISIONS						04/19/21				Shirley	



Pb-free Soldering IR Reflow(SMD)



- 1,MSL Grade: 1 Level 2,Floor life: 2years 3,Condition:≤30°C RH 85%
2,Form-1(Reference JEDEC J-STD-020D Table 5-2)

IR reflow profile		Pb-free
step#	Profile Feature	Condition/Duration
step1	Ramp-up rate	3°C/second max
step2	Preheat:150°C-200°C(Ta-Tb)	t1-t2:60-120seconds
step3	Ramp-up rate(TL to Tp)	3°C/second max
	Temperature maintained above 217°C	60-150seconds
step4	Peak temperature(Tp)	260+0/-5°C
	Time within 5°C of actual peak temperature	30seconds max
Ramp-down rate(Tp to TL)		6°C/second max

- 3,Form-2(Reference JEDEC J-STD-020D Table 4-2)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6mm	260+0/-5°C	260+0/-5°C	260+0/-5°C
1.6mm-2.5mm	260+0/-5°C	250+0/-5°C	245+0/-5°C
>2.5mm	250+0/-5°C	245+0/-5°C	245+0/-5°C